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**(54) CCD PACKAGE MODULE**

**(57) Abstract:**

**PROBLEM TO BE SOLVED:** To provide a CCD package module for reduced thickness.

**SOLUTION:** Related to a CCD package module 1, a circuit 121 is directly, chiefly, manufactured on the bottom surface of a glass 12 for package combination between an image-taking chip 11 and a flip chip, and a tin ball 13 is used for circuit combination between the circuit 121 and a printed circuit board 16. The thickness of a package module of the image-taking chip of a charge coupled device is reduced by coupling technology of the flip chip, use of a transparent glass substrate to manufacture a circuit for a package, or a coupling technology of the flip chip for combination with various substrate, for the package module of a thin-type CCD image-taking chip.

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